

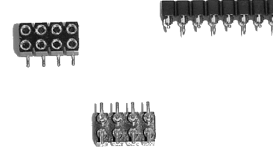
# 1532

## SMT Präz. Buchsenleiste - 1-/2-reihig - RM 2,54 mm - BH 5,6 mm

SMT Precision Female Header - Single and Double Row - Pitch 2,54 mm - Height over Board 5,6 mm

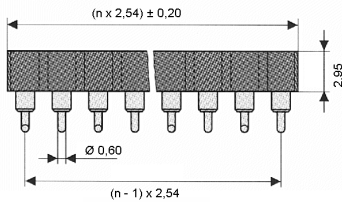
### Technische Daten / Technical Data:

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94V0 <i>Thermoplastic, rated UL94V0</i>
Kontaktmaterial <i>Contact Material</i>	Hülse: Messing gedreht Feder: 6 Lamellen-Clip, Beryllium-Kupfer <i>Sleeve: Screw Machined Brass Clip: 6 Finger-Clip, Beryllium-Copper</i>
Kontaktoberfläche <i>Contact Surface</i>	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm) <i>acc. to options (see below), over Ni (1,3-2,5 µm)</i>
Lötbarkeit <i>Solderability</i>	IEC512-12A <i>IEC512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	≤ 10 mOhm <i>≤ 10 mOhm</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 10 <sup>10</sup> Ohm <i>&gt; 10<sup>10</sup> Ohm</i>
Spannungsfestigkeit <i>Test Voltage</i>	1000 V <sub>RMS</sub> <i>1000 V<sub>RMS</sub></i>
Nennstrom <i>Current Rating</i>	3 A <i>3 A</i>
Temperaturbereich <i>Temperature Range</i>	-55°C...+125°C <i>-55°C...+125°C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren; weitere Informationen in Kapitel T <i>Reflow-Soldering, further informations in chapter T</i>

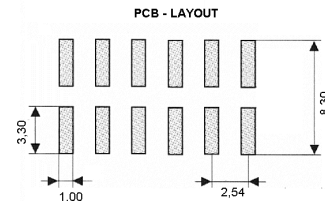
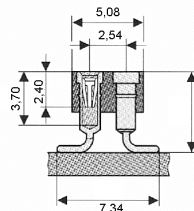
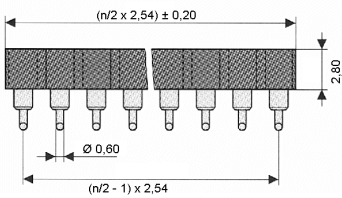
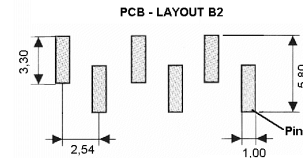
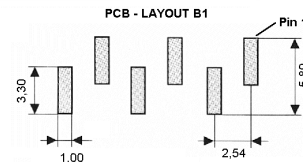
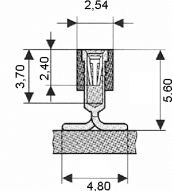


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Passende Stiftleisten Serie:  
*Mates with Pin Headers Series:*  
3531 / 3131 / 3532 / 3132 / 3533 / 3133



n = Anzahl Kontakte  
*n = No. of Contacts*



Series	Contacts*	Rows*	Sleeve Plating	Clip Plating*	Packing*
1532	010 003-032-pol. einreihig <i>single row</i> 004-072-pol. zweireihig <i>double row</i>	1 = einreihig B1 <i>single row B1</i> 2 = einreihig B2 <i>single row B2</i> 3 = zweireihig <i>double row</i>	50 = Hülse verzinkt <i>sleeve tin plated</i>	10 = Feder vergoldet <i>gold plated</i> 00 = Feder 0,25 µm Gold <i>0,25 µm gold plated</i> 30 = Feder 0,75 µm Gold <i>0,75 µm gold plated</i>	00 ST PPST PPTR

**Lieferformen / Packing Options:**  
 00 = Schüttgut ohne PP-Pad / *bulk goods w/o PP-Pad*  
 ST = verpackt in Stangen / *packed in tubes*  
 PPST = in Stangen mit PP-Pad / *in tubes w/ PP-Pad*  
 PPTR \*\* = mit PP-Pad, Tape & Reel Verpackung / *Tape & Reel Packing w/ PP-Pad*  
 (\*\* auf Anfrage / *upon request*)

(\* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.  
\* *Order example - To be replaced by your specifications.*)

# Informationen zum Reflow-Lötverfahren

## Reflow-Soldering Informations

### Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Lötten
Durchschnitts-Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C / Sek. Max.
Vorheizen - Temperatur Min ( $T_{s_{min}}$ ) - Temperatur Max ( $T_{s_{max}}$ ) - Zeit ( $t_{s_{min}}$ auf $t_{s_{max}}$ )	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur ( $T_L$ ) - Zeit ( $t_L$ )	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur ( $T_p$ )	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur ( $t_p$ )	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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*Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):*

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C / second max.
Preheat - Temperature Min ( $T_{s_{min}}$ ) - Temperature Max ( $T_{s_{max}}$ ) - Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )	150°C 200°C 60-180 seconds
Time maintained above: - Temperature ( $T_L$ ) - Time ( $t_L$ )	217°C 60-150 seconds
Peak/Classification Temperature ( $T_p$ )	260°C +/- 5°C
Time within 5°C of actual Peak Temperature ( $t_p$ )	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

*Recommended Reflow-Soldering profile:*



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